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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.	
10/808,540	. 03/25/2004	Ryu Ohtaguro	Q80708	4872	
65565 SUGHRUE-265	7590 01/18/2007 5550		EXAMINER		
2100 PENNSY	LVANIA AVE. NW		ROSASCO, STEPHEN D		
WASHINGTO	N, DC 20037-3213		ART UNIT	PAPER NUMBER	
			1756		
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SHORTENED STATUTOR	Y PERIOD OF RESPONSE	MAIL DATE	DELIVERY MODE		
3 MO	NTHS	01/18/2007	PAPER		

Please find below and/or attached an Office communication concerning this application or proceeding.

If NO period for reply is specified above, the maximum statutory period will apply and will expire 6 MONTHS from the mailing date of this communication.

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		Applicat	ion No.	Applicant(s)				
Office Action Summary		10/808,	540	OHTAGURO ET	AL.			
		Examine	r	Art Unit				
		·	Rosasco	1756	•			
The I Period for Repl	MAILING DATE of this communi	cation appears on th	e cover sheet wit	h the correspondence ac	ddress			
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WHICHEVE - Extensions of t after SIX (6) M - If NO period fo Failure to reply Any reply recei	R IS LONGER, FROM THE MA ime may be available under the provisions of ONTHS from the mailing date of this commit reply is specified above, the maximum state within the set or extended period for reply of ved by the Office later than three months afterm adjustment. See 37 CFR 1.704(b).	AILING DATE OF T of 37 CFR 1.136(a). In no e unication. tutory period will apply and will, by statute, cause the ap	CHIS COMMUNIC event, however, may a re will expire SIX (6) MONT epplication to become ABA	ATION. ply be timely filed THS from the mailing date of this of the candidate of this candidate.	,			
Status								
1)⊠ Respo	nsive to communication(s) filed	d on 15 December :	2006					
	, ,	b)⊠ This action is						
· <u> </u>	Since this application is in condition for allowance except for formal matters, prosecution as to the merits is							
	in accordance with the practic			•				
Disposition of (Claims							
4) Claim(s) <u>1-14</u> is/are pending in the a	pplication.						
	4a) Of the above claim(s) is/are withdrawn from consideration.							
	s) is/are allowed.							
6)⊠ Claim(s) <u>1-14</u> is/are rejected.							
7)∐ Claim(s) is/are objected to.							
8) Claim(s) are subject to restrict	tion and/or election	requirement.					
Application Pap	pers							
9)∏ The sp	ecification is objected to by the	Examiner.						
10)⊠ The dra	awing(s) filed on <u>04 August 200</u>	<u>04</u> is/are: a)⊠ acce	epted or b)⊟ obj	ected to by the Examine	er.			
Applica	int may not request that any objec	tion to the drawing(s)	be held in abeyand	ce. See 37 CFR 1.85(a).				
Replac	ement drawing sheet(s) including	the correction is requi	red if the drawing(s	s) is objected to. See 37 Cl	FR 1.121(d).			
11) <u></u> The oa	th or declaration is objected to	by the Examiner. N	ote the attached	Office Action or form P7	ΓΟ-152.			
Priority under 3	5 U.S.C. § 119							
	vledgment is made of a claim f b) Some * c) None of:	or foreign priority ur	nder 35 U.S.C. §	119(a)-(d) or (f).				
	Certified copies of the priority of	documents have be	en received.					
	Certified copies of the priority of			plication No				
_	Copies of the certified copies of				Stage			
i	application from the Internation	nal Bureau (PCT Ru	le 17.2(a)).					
* See the	attached detailed Office action	for a list of the cert	tified copies not r	eceived.				
Ada a bara a sada b								
Attachment(s)	rences Cited (PTO-892)		A) 🔲 lete adour Co	mman, (PTO 442)				
	rences Cited (P1O-692) Isperson's Patent Drawing Review (P1	ГО-948)	4) Interview Su Paper No(s).	/Mail Date				
	sclosure Statement(s) (PTO/SB/08) lail Date 3/25/04.		5) Notice of Inf 6) Other:	formal Patent Application				
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Detailed Action

Claims are objected to because of the following informalities:

Claim 1 – reads, "A substrate for a substrate", second occurrence should be mask as based on the other claims. But even "substrate for a mask" is unclear. It is a substrate for making a mask; language along these lines would be more accurate.

The claims also use the terms "top" and "back" to refer to the substrate, however, it is unclear from the specification and the drawings which are not labeled with these terms if the back refers to the side opposite the top or is it a side surface. If it is the side opposite the "top" then the term –bottom would have been more appropriate.

Appropriate correction is required.

The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless -

(b) the invention was patented or described in a printed publication in this or a foreign country or in public use or on sale in this country, more than one year prior to the date of application for patent in the United States.

Claims 1-10 are rejected under 35 U.S.C. 102(b) as being anticipated by Takahashi et al. (6,096,405).

Takahashi et al. teach (col. 8, lines 1-24) the limitations of claims 1-14.

The surface roughness (Ra, Rmax) of the peripheral side area 2 of the glass substrate 1 at the intermediate region (chamfered portion) B (length: 0.15 mm), the intermediate region (chamfered portion) C (length: 0.15 mm) and the side end wall A (length: 0.35 mm) are shown in Table 1. In Table 1, the surface roughness Ra of the intermediate region B is 0.2 mu.m, while the surface roughness Rmax of the intermediate

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region B is 1.9 mu.m. Further, the surface roughness Ra of the intermediate region C is 0.15 mu.m, while the surface roughness Rmax of the intermediate region C is 2.9 mu.m. In addition, the surface roughness Ra of the side end wall A is 0.35 mu.m, while the surface roughness Rmax of the side end wall A is 3.4 mu.m. Also, the principal surface 3 of the glass substrate 1 has the surface roughness Ra of 0.5-1 nm.

The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.

Claims 1-14 are rejected under 35 U.S.C. 103(a) as being unpatentable over Tanabe (6,555,273) in view of Takahashi et al. (6,096,405).

The claimed invention is directed to a substrate for substrate comprising: a top surface and a back surface, the surfaces being square in shape; an end surface formed along the thickness thereof; and a chamfered surface formed on a perimeter edge region where the end surface and the top surface meet and another region where the end surface and the back surface meet, wherein a size of the perimeter edge of the substrate is 300 mm or more on a side and the end surface and the chamfered surface each has a roughened surface having a surface roughness (Ra) ranging from 0.03-0.3 mum.

And wherein the end surface and the chamfered surface each has a roughened surface having a surface roughness (Ra) ranging from 0.05-0.3 mum.

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Tanabe teaches (see claims and Fig. 1F) a method of manufacturing a photomask blank by preparing a glass substrate for the photomask blank and depositing a thin film having at least a light shielding function on a principal surface of the glass substrate, wherein the surface of said glass substrate includes at least a pair of principal surfaces parallel to each other, at least a pair of side surfaces perpendicular to the principle surfaces, and at least one chamfered surface interposed between a principal surface and at least one side surface, said principal and said side surfaces being subjected to precision polishing.

The teachings of Tanabe differ from those of the applicant in that the applicant teaches a specific surface roughness for the substrate surfaces and edges.

Takahashi et al. teach (col. 8, lines 1-24) the limitations of claims 1-14.

The surface roughness (Ra, Rmax) of the peripheral side area 2 of the glass substrate 1 at the intermediate region (chamfered portion) B (length: 0.15 mm), the intermediate region (chamfered portion) C (length: 0.15 mm) and the side end wall A (length: 0.35 mm) are shown in Table 1. In Table 1, the surface roughness Ra of the intermediate region B is 0.2 mu.m, while the surface roughness Rmax of the intermediate region B is 1.9 mu.m. Further, the surface roughness Ra of the intermediate region C is 0.15 mu.m, while the surface roughness Rmax of the intermediate region C is 2.9 mu.m. In addition, the surface roughness Ra of the side end wall A is 0.35 mu.m, while the surface roughness Rmax of the side end wall A is 0.35 mu.m, while the surface roughness Rmax of the side end wall A is 3.4 mu.m. Also, the principal surface 3 of the glass substrate 1 has the surface roughness Ra of 0.5·1 nm.

Takahashi et al. also teach that with this structure, no particles are generated from the peripheral side area because the side end surface of the glass substrate is mirror

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finished. Consequently, reproduction is performed without reproduction errors because of no generation of a thermal asperity and a head crash can be sufficiently avoided because of no projections which might result from the particles.

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Therefore, it would have been obvious to one having ordinary skill in the art to take the teachings of Tanabe and combine them with the teachings of Takahashi et al. in order to make the claimed invention because the teachings of Takahashi et al. are directed to the same benefit to which the claimed invention is directed.

Conclusion

Any inquiry concerning this communication or earlier communications from the Examiner should be directed to Stephen Rosasco whose telephone number is (571) 272-1389. The Examiner can normally be reached Monday-Friday, from 8:00 AM to 4:30 PM. The Examiner's supervisor, Mark Huff, can be reached on (571) 272-1385. The fax phone number for the organization where this application or proceeding is assigned is (571) 273-8300.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

S. Rosasco

Primary Examiner

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S.Rosasco 1/09/07